

# bq51013xEVM-764 Evaluation Module (WCSP Package)

The bq51013xEVM (HPA764-001 and HPA764-003) wireless power receiver evaluation kit from TI is a high-performance, easy-to-use development kit for the design of wireless power solutions. It helps designers to evaluate the operation and performance of the bq51013A and bq51013B, 5-V power supply for wireless power transfer. The bq51013A and bq51013B devices provide the AC/DC power conversion and regulation while integrating the digital control required to comply with the Qi communication protocol. The kit speeds up the development of end-use applications.

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### 1 Considerations with this EVM

The bq51013xEVM-764 evaluation module (HPA764-001 and 003) demonstrates the receiver portion of the bqTESLA™ wireless power system. This receiver EVM is a complete receiver-side solution that produces 5-V output at up to 1-A load.

- The bqTESLA receiver is used in any number of low-power battery portable devices such as a direct battery charger. With contact-free charging capability, no connections to the device are needed.
- Output voltage of 5 V up to 1-A charge current
- · External adapter switchover
- · Low-profile, external pick-up coil
- Frame is configured to provide correct receiver to transmitter spacing
- Room above coil for testing with battery, key for tuning
- Option to adjust the max output current using variable resistor R16

#### 2 Modifications

Refer to the datasheet when changing components (<u>SLUSAY6</u> for bq51013A and <u>SLUSB62</u> for the bq51013B). To aid in such customization of the EVM, the board was designed with devices having 0603 or larger footprints. A real implementation likely occupies less total board space.

Note that changing components can improve or degrade EVM performance.

#### 3 Recommended Operation Condition

Table 1 provides a summary of the bq51013xEVM-764 performance specifications. All specifications are given for an ambient temperature of 25°C.

Table 1. Table 1. bq51013AEVM-764 Electrical Performance Specifications

| Parameter        |                                    | Test Condition                                    |     | TYP | MAX | UNIT |
|------------------|------------------------------------|---|-----|-----|-----|------|
| V <sub>IN</sub>  | Input voltage range                | Typical Vrect Voltage at TP12                     | 4.0 | 5.5 | 8   | V    |
| Vadapter         | Adapter input voltage              |   | 4.0 | 7   | 20  | V    |
| OVP              | Input<br>overvoltage<br>protection | Voltage at V-rectified                            |     |     | 1.5 | A    |
| I <sub>OUT</sub> | Output current range               | Current limit programming range                   |     |     | 1.5 | Α    |
| V <sub>OUT</sub> | Output voltage                     | I <sub>LOAD</sub> = 1000 mA                       |     | 5   |     | V    |
| Fs               | Switching frequency                |   | 110 |     | 205 | kHz  |
| Efficiency       | AC-DC efficiency                   | 1-A Fast charge current, V <sub>BAT</sub> = 4.2 V |     | 74  |     | %    |



### 4 Equipment and EVM setup

#### 4.1 Schematic

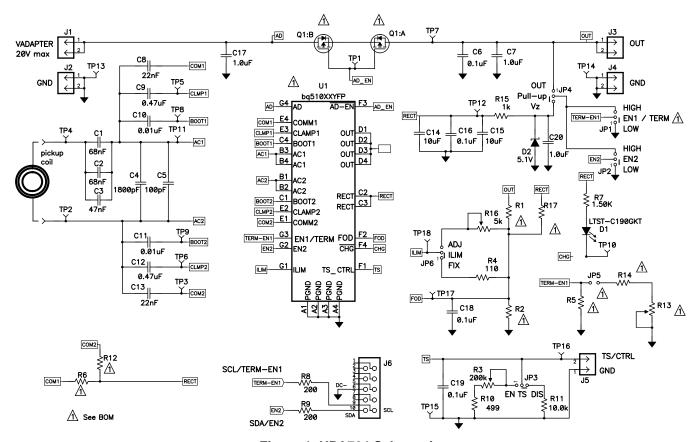


Figure 1. HPA764 Schematic

### 4.2 Connector and Test Point Descriptions

The connection points are described in the following paragraphs.

### 4.2.1 J1 – AD External Adapter Input, J2-GND

Power cannot be provided to simulate an external adapter applied to the receiver in this bq51013xEVM-764 (HPA764).

#### 4.2.2 J3 – Output Voltage, J4-GND

Output voltage is 5 V in wireless power mode up to 1 A; the adapter option is not supported in this HPA764-002.

### 4.2.3 J5 - TS and Return Connector

External connection for temperature sense resistor, see the datasheet for additional information.

## 4.2.4 J6 – Programming Connector

This connector is populated and is only useful at the factory level for programming the IC.



### 4.3 Jumpers and Switches

The control jumpers are described in the following paragraphs.

#### 4.3.1 JP1 – EN1 Enable 1

Not populated in this EVM (HPA764-001 and 003).

#### 4.3.2 JP2 - EN2 Enable 2

Enable signal input that allows the system to assert wireless charging. If EN2 is set to low, wireless charging is enabled unless AD voltage > 3.6 V. If EN2 is set to High, AD mode disabled, wireless charging always enabled. Used when OTG plus wireless charging is active.

#### 4.3.3 JP3 – TS Enable or Disable

This jumper enables the TS adjustment feature using R3. The disable position sets voltage at the TS pin to a safe value. The default shorting jumper setting is disabled.

### 4.3.4 JP4 - Pull-Up to Out or Vz

EN2 pull-up can be powered from OUT or RECT. Vz is derived from RECT through a resistor and Zener diode D2.

#### 4.3.5 JP5 – Termination

This jumper along with R14 and R13 are not installed in HPA764 - 001-003.

#### 4.3.6 JP6 – ILIM Fix or ADJ

Max output current is set by ILIM pin. In the FIX position, the current is set to a fixed value. In the ADJ position the current is set by R16.

#### 4.4 Test Point Descriptions

The test points are described in the following paragraphs.

## 4.4.1 TP1 – AD-EN

This push-pull driver for the external PFET connects the adapter and the output from the bq5101x. This is not useful for the bq5105x.

#### 4.4.2 TP2 - AC Input 2

This is the test point for measuring AC voltage applied to the EVM from the receiver coil.

#### 4.4.3 TP3 - COM2 Communication 2 Drive

Communication driver signal, open-drain output connected to communication capacitor.

#### 4.4.4 TP4 - AC Input 1

This is the test point for measuring AC voltage applied to the EVM from the receiver coil.

#### 4.4.5 TP5 - CLMP 1

Overvoltage clamp driver signal, open-drain output is connected to OVP capacitor.

#### 4.4.6 TP6 - CLMP 2

Overvoltage clamp drive signal, open-drain output is connected to OVP capacitor.



### 4.4.7 TP7 – OUT Output Voltage

This test point is the output voltage from the bq51050B.

#### 4.4.8 TP8 – Boot-1 Boot Capacitor

This bootstrap capacitor 1 drive connects to the integrated circuit (IC).

#### 4.4.9 TP9 - Boot-2 Boot Capacitor

This bootstrap capacitor 2 drive connects to the IC.

### 4.4.10 TP10 - CHG Charge

This output signal indicates that the output current is being delivered to OUT, the open-drain output.

### 4.4.11 TP11 - AC1 IC input

This is the AC input to the IC from series capacitors.

### 4.4.12 TP12 – Rectified Voltage

The input AC voltage is rectified into unregulated DC voltage; additional capacitance is used to filter the voltage before the regulator.

### 4.4.13 TP13, TP14, TP15 - GND

These are the ground test points.

#### 4.4.14 TP16 – TS Temp Sensor

This is the connection point for external thermistor; see the data sheet for additional information.

#### 4.4.15 TP17 – FET Open Detection (FOD)

Input for rectified power measurement, pin F2 of the IC.

### 4.4.16 TP18- ILIM

Programming pin for over current limit, pin G1 of the IC.

### 4.5 Pin Description of the IC

**Table 2. Pin Description** 

| PIN Number (WCSP) | bq51013B and bq51013A |
|-------------------|-----------------------|
| A1, A2, A3, A4    | PGND                  |
| B1, B2            | AC2, AC2              |
| B3, B4            | AC1, AC1              |
| C1                | BOOT2                 |
| C2, C3            | RECT                  |
| C4                | BOOT1                 |
| D1, D2, D3, D4    | OUT                   |
| E1                | COM2                  |
| E2                | CLMP2                 |
| E3                | CLMP1                 |
| E4                | COM1                  |
| F1                | TS/CTRL               |



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**Table 2. Pin Description (continued)** 

| PIN Number (WCSP) | bq51013B and bq51013A |
|-------------------|-----------------------|
| F2                | FOD                   |
| F3                | AD-EN                 |
| F4                | CHG                   |
| G1                | ILIM                  |
| G2                | EN2                   |
| G3                | EN1                   |
| G4                | AD                    |

### 5 Test Procedure

This procedure describes test configuration of the bq51013B evaluation board (HPA764-003) for bench evaluation.

#### 5.1 Definition

The following naming conventions are used:

**VXXX**: External voltage supply name (VADP, VBT, VSBT)

LOADW: External load name (LOADR, LOADI)

V(TPyy): Voltage at internal test point TPyy. For example, V(TP02) means the voltage at TP02.

V(Jxx): Voltage at header Jxx

**V(TP(XXX)):** Voltage at test point XXX. For example, V(ACDET) means the voltage at the test point which is marked as ACDET.

**V(XXX, YYY):** Voltage across point XXX and YYY.

**I(JXX(YYY)):** Current going out from the YYY terminal of header XX.

Jxx(BBB): Terminal or pin BBB of header xx.

**JPx ON:** Internal jumper Jxx terminals are shorted.

**JPx OFF**: Internal jumper Jxx terminals are open.

JPx (-YY-) ON: Internal jumper Jxx adjacent terminals marked as YY are shorted.

Assembly drawings have location for jumpers, test points, and individual components.

### 5.2 Recommended Test Equipment

The following equipment is needed to complete this test procedure.

#### 5.2.1 Power Supplies

A power supply capable of supplying 19 V at 1 A is required for testing procedures.

#### 5.2.2 Loads

A resistive load or electronic load set to 5  $\Omega$  at 1 A, 10  $\Omega$  at 500 mA, and 5 k $\Omega$  at 1 mA, power rating should be 5 W.

#### 5.2.3 Meters

Two DC voltmeters and two DC ammeters are required.



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#### 5.2.4 bqTesla Transmitter

The transmitter HPA689 or equivalent is used for final test.

### 5.3 Equipment Setup

#### 5.3.1 Test Set Up

The final assembly is tested using a bqTesla transmitter, provided (HPA689). Input voltage to the transmitter is set to 19  $V_{DC}$  ±200 mV with a current limit of 1.0 A and connection to J1 and J2. Set the power supply to OFF. Place UUT on the transmitter coil. Unit under test is placed in the center of the HPA689 TX coil.

Other bgTesla transmitter base units are also acceptable for this test.

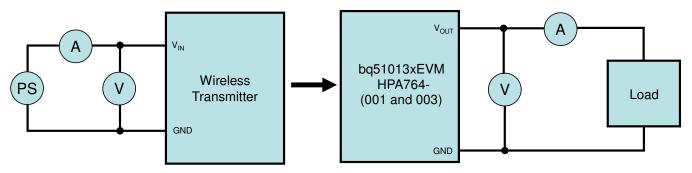


Figure 2. Test Set up

#### 5.3.2 Load

The load is connected between J3 - OUT and J4 - GND of the UUT. A DC ammeter is connected between UUT and Load. Set the load for 10  $\Omega$  at 500 mA.

## 5.3.3 Jumper Settings

JP1 → EN1/TERM and LOW shorted

JP2 → EN2 and LOW shorted

 $JP3 \rightarrow TS$  and DIS shorted

JP4 → Pullup and Vz shorted

JP5 → Open

 $JP6 \rightarrow ILIM$  and ADJ shorted

#### **5.3.4** Meters

- Connect ammeter to measure 19-V input current to transmitter.
- Connect voltmeter to monitor input voltage at J1 and J2 of TX unit.
- On UUT, a voltmeter is used to measure output voltage at TP7 with ground at J4.
- · Connect ammeter to measure load current.

### 5.3.5 R3 Set Up

Connect ohmmeter across J5. Connect shorting jumper JP3 from TS to EN. Adjust R3 for a 10 k $\Omega$ ,  $\pm 200$ - $\Omega$  reading on the ohmmeter.

#### 5.3.6 R16 Set Up

Connect ohmmeter between JP6 - ADJ and J2 - GND. Adjust R16 for 300  $\Omega$ , ±20- $\Omega$  reading on the ohmmeter.



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#### 5.4 Procedure

#### 5.4.1 Turn ON Operation and Operation at 500 mA Load

- Turn ON transmitter power supply (19 V)
- Transmitter verify LED D2 is ON
- UUT Adjust load current to 500 mA, ±50 mA
- Turn ON emulator PS#2 (3.6 V)
- Put the receiver EVM on the transmitter coil and align them correctly
- · After 5 seconds, verify that:
  - 1. Transmitter status LED D5 is flashing green ~ 1 s
  - 2. The transmitter beeps
  - 3. Transmitter LED D2 is still ON
  - 4. Receiver LED D1 is ON
- UUT Verify that V<sub>OUT</sub> is 4.9 V to 5.1 V (Between J3 or TP7 and J4)
- UUT Verify that rectified voltage should be 5.1 V to 5.25 V (between TP12 and TP13) (Note: a
  modulation signal is present on this voltage every 250 milliseconds and may cause fluctuation in the
  reading use lower value or base line)

#### 5.4.2 Efficiency Test (500-mA Load)

- Verify that the input current to TX is less than 210 mA with input voltage at 19 V<sub>DC</sub>
- Turn OFF transmitter power supply

#### 5.4.3 Operation (1-mA Load)

- Turn ON transmitter power supply
- Transmitter Verify LED D2 is ON
- UUT Adjust load current to 1 mA, ±200 μA
- · Put the receiver EVM on the transmitter coil and align them correctly
- After 5 seconds, verify that:
  - 1. Transmitter status LED D5 is flashing green ~ 1 second
  - 2. The transmitter beeps
  - 3. Transmitter LED D2 is still ON
  - 4. Receiver LED D1 is ON
- UUT Verify that V<sub>OUT</sub> is 4.9 V to 5.1 V (Between J3 or TP7 and J4)
- UUT Verify that rectified voltage is 6.9 V to 7.5 V (between TP12 and TP13) (Note: a modulation signal is present on this voltage every 250 milliseconds and may cause fluctuation in the reading use lower value or base line)

#### 5.4.4 Operation (1-A Load)

- UUT Adjust load current to 00 mA, ±50 mA
- UUT Verify that V<sub>OUT</sub> is 4.9 V to 5.1 V (Between J3 or TP7 and J4)
- UUT Verify that rectified voltage is 5.0 V to 5.2 V (between TP12 and TP13) (Note: a modulation signal is present on this voltage every 250 milliseconds and may cause fluctuation in the reading use lower value or base line)

#### 5.4.5 Efficiency Test (1-A Load)

- $\bullet$  Verify that the input current to TX is less than 380 mA with input voltage at 19  $V_{DC}$
- Turn OFF transmitter power supply



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### 5.4.6 Adapter Test (500-mA Load)

- Connect a 6-V, ±200-mV power supply with a current limit set to 1.0 A to J1 and return to J2.
- Adjust load current to 500 mA, ±50 mA
- Turn on power supply
- Verify that:
  - 1. UUT LED D1 is OFF
  - 2. UUT TP7  $V_{OUT}$  is 5.75 V to 6 V
  - 3. Transmitter Status LED D5 is OFF

#### 6 Test Results

### 6.1 Load Step

The procedure for load step is as follows:

- Set up the test bench as described in Section 5.
- Power TX with 19 V.
- Provide a load step from no load (high impedance) to 10 Ω or 500 mA (if using current source load).
- Monitor load current, rectifier voltage, and output voltage as shown in Figure 3.

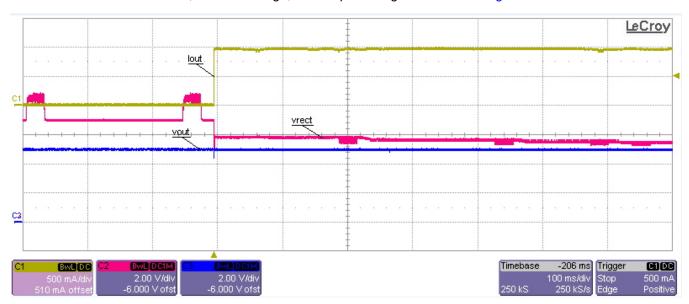


Figure 3. Load Step, 0 mA to 500 mA

### 6.2 Load Dump

The procedure for load dump is as follows:

- Set up the test bench as described in Section 5.
- Power TX with 19 V
- Provide a load dump from 10ohms or 500 mA (if using a current source load) to no load (high impedance).
- Monitor load current, rectifier voltage, and output voltage as shown in Figure 4.



Test Results www.ti.com



Figure 4. Load Dump, 500 mA to 0 mA

## 6.3 Start-Up

These procedures demonstrates start-up:

- Set up the test bench as described in Section 5.
- Power TX with 19 V
- Trigger scope sweep on TP2 AC IN

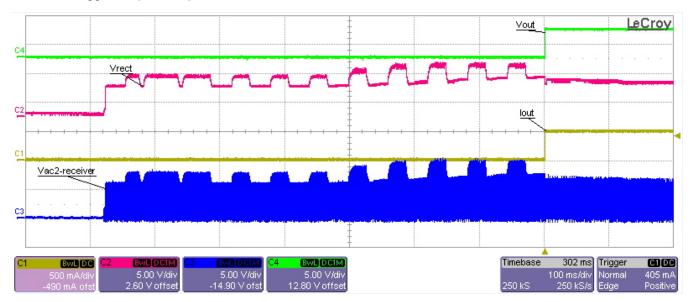


Figure 5. Start-Up



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### 6.4 Efficiency

Figure 6 shows the efficiency data for the discrete solution using the wireless receiver, bq51013A, and a charger, bq24168. The efficiency data are measured across battery voltage from 0.5 V to 4.2 V. The data reveals that the efficiency of the receiver is around 86% and the charger efficiency can reach as high as 90% at regulation.

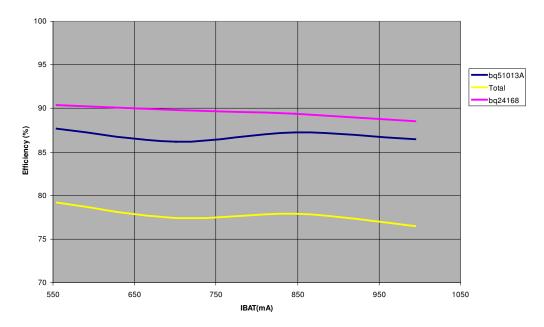


Figure 6. Efficiency for the bq51013A vs. IBAT

#### 6.5 Thermal Performance

This section shows a thermal image of the bq51013BEVM-764. A 5.0-V output is used at a 1000-mA load. There is no air flow and the ambient temperature is 25°C. The peak temperature of the IC, 49.9°C, is well below the maximum recommended operating condition listed in the data sheet.

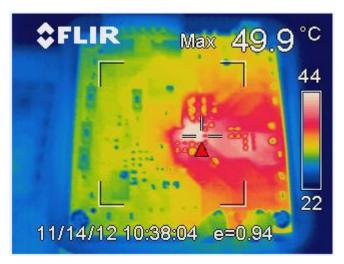


Figure 7. Thermal Image



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### 6.6 WPC 1.1 certification

The bq51013BEVM-764 WPC 1.1 certification is shown in Figure 8.



Figure 8. WPC 1.1 Certification for the bq51013BEVM-764



### 7 Layout and Bill of Material

### 7.1 Layout

### 7.1.1 Printed-Circuit Board Layout Guideline

The primary concerns when laying out a custom receiver PCB are:

- AC1 and AC2 trace resistance
- OUT trace resistance
- RECT trace resistance
- · GND connection
- Copper weight ≥ 2 oz

For a 1-A load current application, the current rating for each net is as follows:

- AC1 = AC2 = 1.2 A
- BOOT1 = BOOT2 = 10 mA
- RECT = 1 A
- OUT = 1 A
- COM1 = COM2 = 300 mA
- CLAMP1 = CLAMP2 = 500 mA
- ILIM = 10 mA
- AD = AD\_EN = TS-CTRL = EN1 = EN2 = TERM = FOD = 1 mA
- CHG = 10 mA

It is also recommended to have the following capacitance on RECT and OUT:

- RECT ≥ ±10 µF
- OUT ≥ 1 µF

It is always a good practice to place high-frequency bypass capacitors of 0.1 µF next to RECT and OUT. Figure 9 illustrates an example of a WCSP layout:

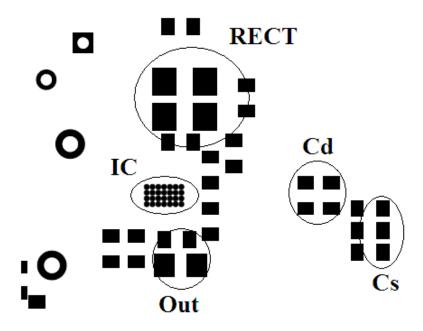


Figure 9. bq51013BEVM Layout Example



### 7.1.2 Layout

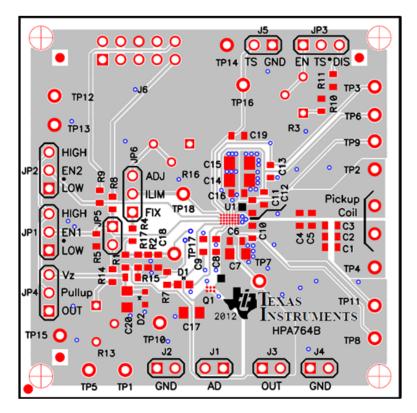


Figure 10. bq51050BEVM-764 Top Assembly

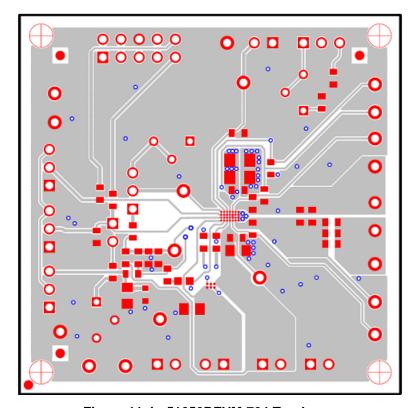


Figure 11. bq51050BEVM-764 Top Layer



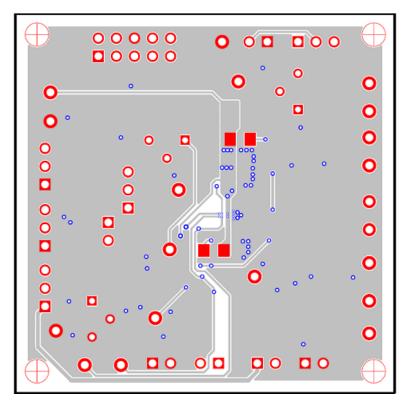


Figure 12. bq51050BEVM-764 Bottom Copper Layer

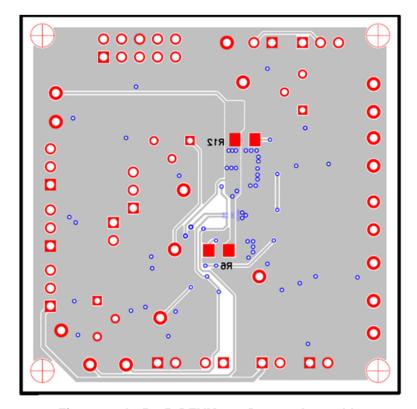


Figure 13. bq51050BEVM-764 Bottom Assembly



Layout and Bill of Material www.ti.com

## 7.2 Bill of Materials (BOM)

## Table 3. bq51013BEVM-764 Bill of Materials

| 001 | 003 | RefDes  | Value         | DESCRIPTION   | SIZE               | Part Number      | MFR          |
|-----|-----|---|---------------|---|--------------------|------------------|--------------|
| 2   | 2   | C1, C2  | 68nF          | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 1   | 1   | СЗ  | 47nF          | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 1   | 1   | C4  | 1800pF        | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 1   | 1   | C5  | 100pF         | Capacitor, Ceramic, 50V, C0G, 5%                                | 0603               | Std              | Std          |
| 4   | 4   | C6, C16, C18, C19   | 0.1uF         | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 3   | 3   | C7, C17, C20  | 1.0uF         | Capacitor, Ceramic, 50V, X5R, 10%                               | 0805               | Std              | Std          |
| 2   | 2   | C8, C13   | 22nF          | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 2   | 2   | C9, C12   | 0.47uF        | Capacitor, Ceramic, 25V, X5R, 10%                               | 0603               | Std              | Std          |
| 2   | 2   | C10, C11  | 0.01uF        | Capacitor, Ceramic, 50V, X7R, 10%                               | 0603               | Std              | Std          |
| 2   | 2   | C14, C15  | 10uF          | Capacitor, Ceramic, 25V, X5R, 10%                               | 1206               | Std              | Std          |
| 1   | 1   | D1  | LTST-C190GKT  | Diode, LED, Green, 2.1-V, 20-mA, 6-mcd                          | 0603               | LTST-C190GKT     | Lite On      |
| 1   | 1   | D2  | 5.1V          | Diode, Zener, 5.1V, 300mW                                       | SOD-523            | BZT52C5V1T-7     | Diodes, Inc. |
| 5   | 5   | J1, J2, J3, J4, J5  | PEC02SAAN     | Header, Male 2-pin, 100mil spacing,                             | 0.100 inch x 2     | PEC02SAAN        | Sullins      |
| 1   | 1   | J6  | N2510-6002-RB | Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall        | 0.338 x 0.788 inch | N2510-6002-RB    | 3M           |
| 4   | 4   | JP2, JP3, JP4, JP6  | PEC03SAAN     | Header, Male 3-pin, 100mil spacing,                             | 0.100 inch x 3     | PEC03SAAN        | Sullins      |
| 1   | 1   | JP1   | PEC03SAAN     | Header, Male 3-pin, 100mil spacing,                             | 0.100 inch x 3     | PEC03SAAN        | Sullins      |
| 0   | 0   | JP5   | PEC02SAAN     | Header, Male 2-pin, 100mil spacing,                             | 0.100 inch x 2     | PEC02SAAN        | Sullins      |
| 1   | 1   | Q1  | CSD75205W1015 | MOSFET, Dual PChan, -20V, 1.2A, 190 milliOhm                    | CSP 1x1.5mm        | CSD75205W1015    | TI           |
| 0   | 0   | R1  | Open          | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 0   | R2  | 150           | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 0   | 1   | R2  | 196           | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 1   | R3  | 200k          | Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust              | 0.25x0.17          | 3266W-1-204LF    | Bourns       |
| 1   | 1   | R4  | 75 Ω          | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 0   | 0   | R5  | Open          | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 0   | 0   | R6, R12   | Open          | Resistor, Metal Film, 1/4 watt, ± 1%                            | 1206               | CRCW120624R0FKEA | Vishay       |
| 1   | 1   | R7  | 1.50K         | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 1   | R8, R9  | 200           | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 1   | R10   | 499           | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 1   | R11   | 10.0k         | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 0   | 0   | R14   | 1.0k          | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 1   | 1   | R15   | 1.0K          | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 0   | 0   | R13   | 20k           | Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust              | 0.25x0.17          | 3266W-1-203LF    | Bourns       |
| 1   | 1   | R16   | 5k            | Potentiometer, 1/4 in. Cermet, 12-Turn, Top-Adjust              | 0.25x0.17          | 3266W-1-502LF    | Bourns       |
| 0   | 1   | R17   | 20K           | Resistor, Chip, 1/16W, 1%                                       | 0603               | Std              | Std          |
| 15  | 15  | TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP16, TP17, TP18 | 5000          | Test Point, Red, Thru Hole Color Keyed                          | 0.100 x 0.100 inch | 5000             | Keystone     |
| 3   | 3   | TP13, TP14, TP15  | 5001          | Test Point, Black, Thru Hole Color Keyed                        | 0.100 x 0.100 inch | 5001             | Keystone     |
| 1   | 0   | U1  | bq51013AYFP   | IC, Wirless Secondary-Side Power Controller and Battery Charger | DSBGA              | bq51013AYFP      | TI           |



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## Table 3. bq51013BEVM-764 Bill of Materials (continued)

| 001 | 003    | RefDes   | Value   | DESCRIPTION   | SIZE        | Part Number                                     | MFR                    |  |  |
|-----|--------|--|---|---|-------------|---|------------------------|--|--|
| 0   | 1      | U1   | bq51013BYFP   | IC, Wirless Secondary-Side Power Controller and Battery Charger | DSBGA       | bq51013BYFP                                     | TI                     |  |  |
| 5   | 5      |  |   | Shunt, 100-mil, Black   |             | 929950-00                                       | 3M                     |  |  |
| 1   | 1      |  |   | PCB, 2.1" x 2.1" x 0.031"                                       |             | HPA764  | Any                    |  |  |
| 1   | 1      |  |   | Case Modified Polycase LP-11B with 4 screwsSee note 7           |             | J-6838A   | Polycase               |  |  |
| 1   | 1      |  |   | Coil, RX with Attractor - See note 8.                           |             | IWAS-4832FF-50<br>WR-483250-15M2-G<br>760308201 | Vishay<br>TDK<br>Wyrth |  |  |
| 1   | 1      |  |   | Tape segment, Low Static Polyimide Film - See note 6.           | 1.5" x 2.3" | 5419-1 1/2"                                     | 3M                     |  |  |
|     | Notes: |  |   |   |             |   |                        |  |  |
|     |        | 1. These assemblies are ESD sensitive,   | 1. These assemblies are ESD sensitive, observe ESD precautions.   |   |             |   |                        |  |  |
|     |        | 2. These assemblies must be clean and  | 2. These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable |   |             |   |                        |  |  |
|     |        | 3. These assemblies must comply with v   | 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.                                     |   |             |   |                        |  |  |
|     |        | 4. Reference designators marked with an asterisk ('**') cannot be substituted. All other components can be substituted with equivalent MFG's components. |   |   |             |   |                        |  |  |
|     |        | 5. Tape "Coil, RX" into bottom of case, centered, coil side down, lead wires passing through milled groove.  |   |   |             |   |                        |  |  |
|     |        | 6. Secures RX coil to case. Cut tape section from 36 yard roll identified in part number field.  |   |   |             |   |                        |  |  |
|     |        | 7. Install PCB in the case using provided screws.  |   |   |             |   |                        |  |  |
|     |        | 8. Other coil type can be used.  |   |   |             |   |                        |  |  |

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As noted in the EVM User's Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs **not** subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

#### General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

### For EVMs annotated as FCC - FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

#### Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

#### FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

#### For EVMs annotated as IC - INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

### Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

### [Important Notice for Users of EVMs for RF Products in Japan]

#### This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

- Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
- 3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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# EVALUATION BOARD/KIT/MODULE (EVM) WARNINGS, RESTRICTIONS AND DISCLAIMERS

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Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

- 1. You have unique knowledge concerning Federal, State and local regulatory requirements (including but not limited to Food and Drug Administration regulations, if applicable) which relate to your products and which relate to your use (and/or that of your employees, affiliates, contractors or designees) of the EVM for evaluation, testing and other purposes.
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- 3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
- 4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

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